

Title (en)

FORMALDEHYDE-FREE ELECTROLESS COPPER PLATING SOLUTION

Title (de)

FORMALDEHYDFREIE LÖSUNG FÜR STROMLOSE VERKUPFERUNG

Title (fr)

SOLUTION POUR CUIVRAGE AUTOCATALYTIQUE EXEMPTÉ DE FORMALDÉHYDE

Publication

EP 2764135 A2 20140813 (EN)

Application

EP 12766668 A 20121001

Priority

- EP 11183991 A 20111005
- EP 2012069388 W 20121001
- EP 12766668 A 20121001

Abstract (en)

[origin: WO2013050332A2] The invention relates to an electroless aqueous copper plating solution, comprising a source of copper ions, a source of glyoxylic acid as reducing agent, and at least one polyamino disuccinic acid or at least one polyamino monosuccinic acid, or a mixture of at least one polyamino disuccinic acid and at least one polyamino monosuccinic acid as complexing agent, as well as to a method for electroless copper plating utilizing said solution and the use of the solution for the plating of substrates.

IPC 8 full level

C23C 18/40 (2006.01)

CPC (source: EP US)

C23C 18/40 (2013.01 - EP US)

Citation (search report)

See references of WO 2013050332A2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

WO 2013050332 A2 20130411; WO 2013050332 A3 20140313; WO 2013050332 A8 20130711; CN 104040026 A 20140910; CN 104040026 B 20190101; EP 2764135 A2 20140813; JP 2014528517 A 20141027; JP 6180419 B2 20170816; KR 101953940 B1 20190304; KR 20140090145 A 20140716; TW 201323654 A 20130616; TW I557271 B 20161111; US 2014242264 A1 20140828

DOCDB simple family (application)

EP 2012069388 W 20121001; CN 201280049015 A 20121001; EP 12766668 A 20121001; JP 2014533846 A 20121001; KR 20147008668 A 20121001; TW 101136996 A 20121005; US 201214350153 A 20121001